



FEATURES

- IrDA 115 kbit/s Low Power Option Compatible:
 - $I_F = 27$ mA (TYP.) for an operating distance of 20 cm
- Small Package Design for IrDA 115 kbit/s 1 meter Compliant Infrared Transceiver 8.7 (W) × 4.2 (D) × 3.15 (H) mm
- Fits within Mobile Phone Connector Dimensions
- Low Power Consumption and Built-in Shut-Down Mode (1 μ A MAX.)
- Wide Range of Operating Voltages provides power supply design flexibility ($V_{CC} = 2.7$ V to 5.5 V)
- Solder Reflow Compatibility for automated production processes
- SMD Package allows both Vertical and Horizontal mounting on PCBs Description

DESCRIPTION

The SHARP GP2W0001YP is a standard transceiver module. Even at low operating voltages, it provides a reliable interface between logic and IR signals for through-air, serial, half-duplex IR wireless data links and is designed to satisfy IrDA physical layer specifications.

The GP2W0002YP is the same module, and adds an integral Electro-Magnetic Interference (EMI) shield. While IR energy is inherently immune to EMI, the receiving devices themselves are not. This shield provides an additional level of protection in electromagnetically noisy environments such as PCs and other digital products.

The SHARP GP2W0001YP/GP2W0002YP infrared transceiver modules contain a high speed, high efficiency, low power consumption AlGaAs LED, silicon PIN photodiode, and a low power bipolar integrated circuit. The IC contains an LED driver circuit and a receiver, providing the Rx output. IrDA data rates of 2.4 kbit/s to 115.2 kbit/s are supported at both 20 cm and one-meter distances. At the one-meter range, emitter current is approximately $I_F = 300$ mA and in the IrDA Low Power Option communication mode $I_F = 27$ mA. This dual mode communication capability provides wider product applications, such as a wireless data link with PCs, PDAs, or any other IrDA compliant application already on the market.

The GP2W0001YP/GP2W0002YP transceiver modules may be operated over a power supply range of 2.7 V to 5.5 V without any performance degradation. This provides a single part with a wide variety of design applications.

For power-conscious applications, the transceiver module has a built-in Shutdown mode. This reduces the receiver's current consumption to 1 μ A (MAX.) during Shutdown. The transmitter and receiver circuits are separate, allowing the transmitter LED to be driven when in Shutdown mode.

OUTLINE DIMENSIONS

The dimensions shown in Figure 1 and Figure 2 are only for design reference, and are subject to change without notice. The metal shield case version GP2W0002YP, (for excellent noise immunity) is shown in Figure 2. Contact your local SHARP office for the latest device specifications.

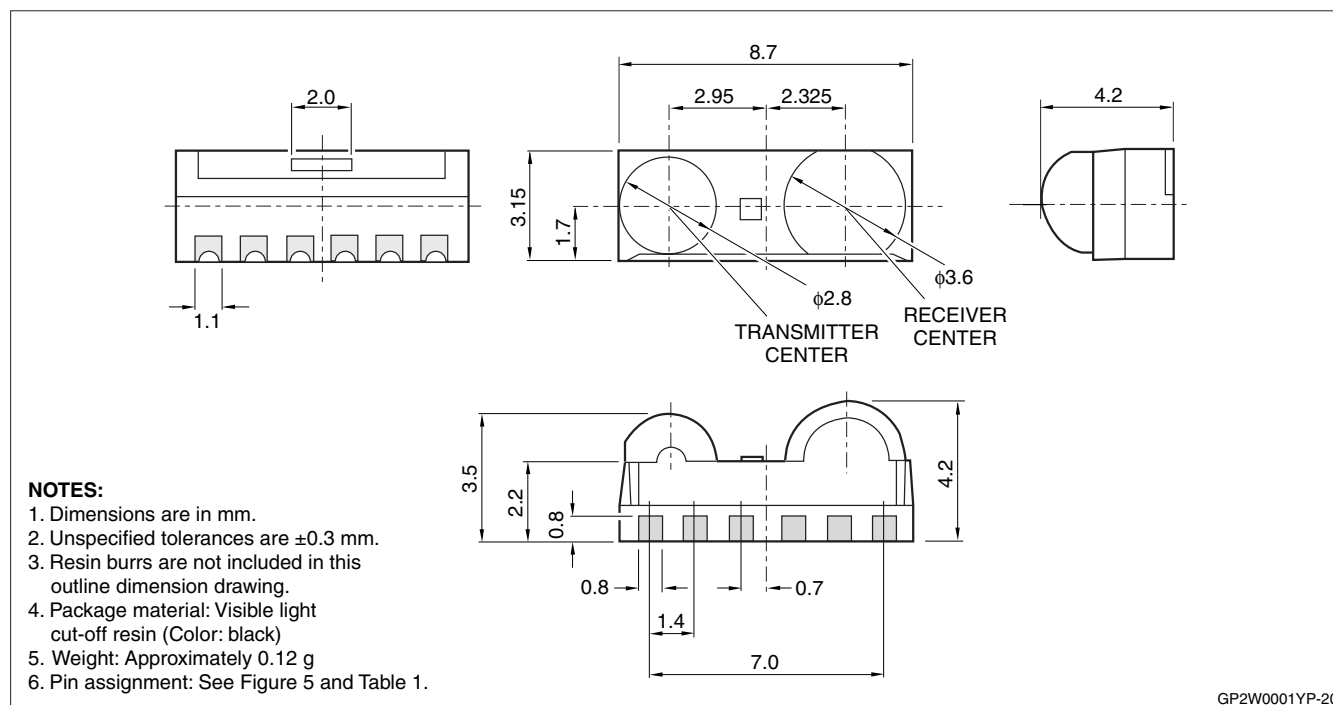


Figure 1. GP2W0001YP Outline Dimensions

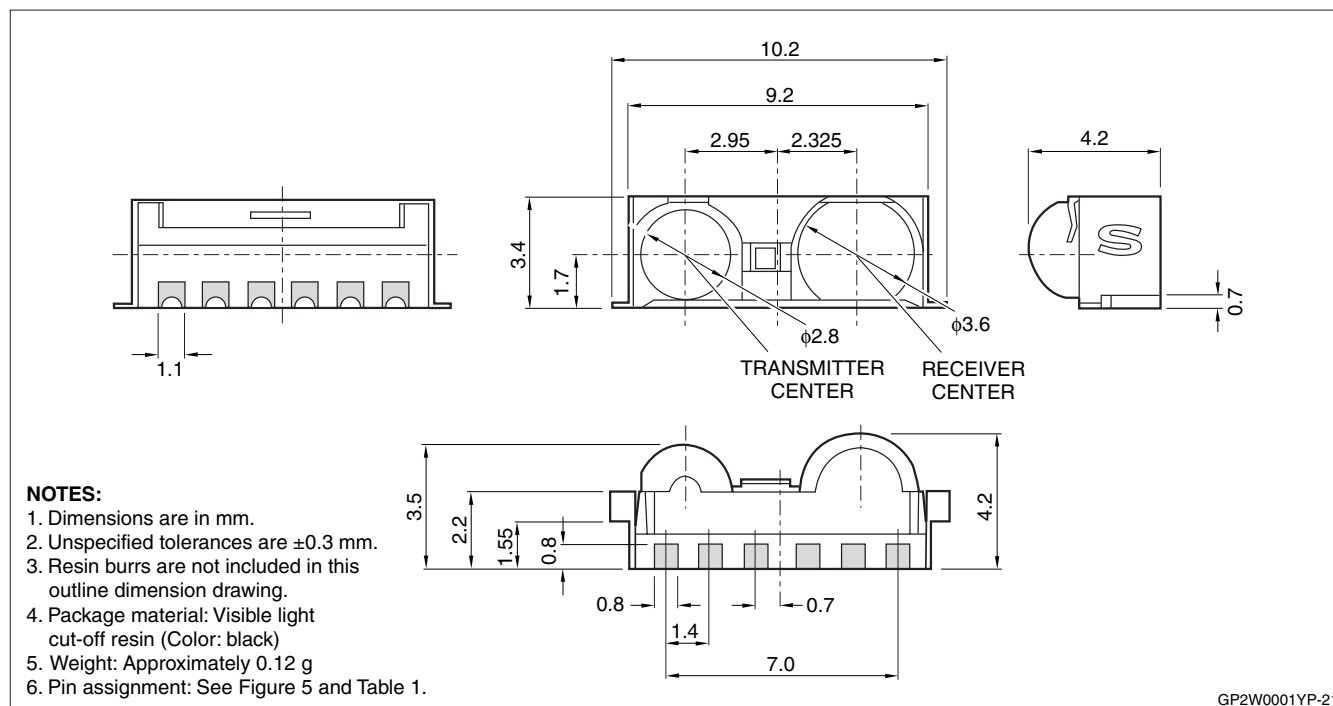


Figure 2. GP2W0002YP (with Shielding Case) Outline Dimensions

Solder Paste Footprints

Figure 3 and Figure 4 are the Solder Paste footprint drawings for both parts. Note that the GP2W0002YP footprint in Figure 4 is compatible with both parts.

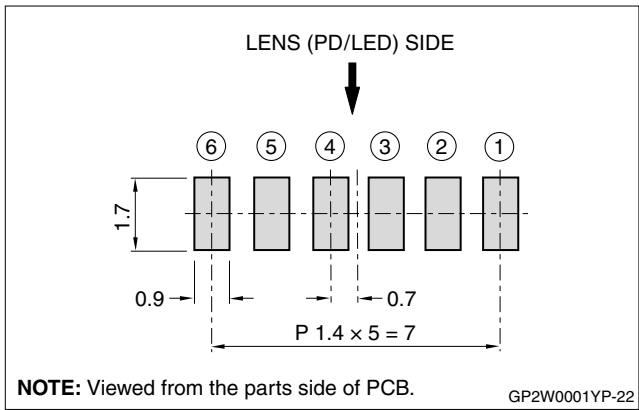


Figure 3. GP2W0001YP Soldering Footprint

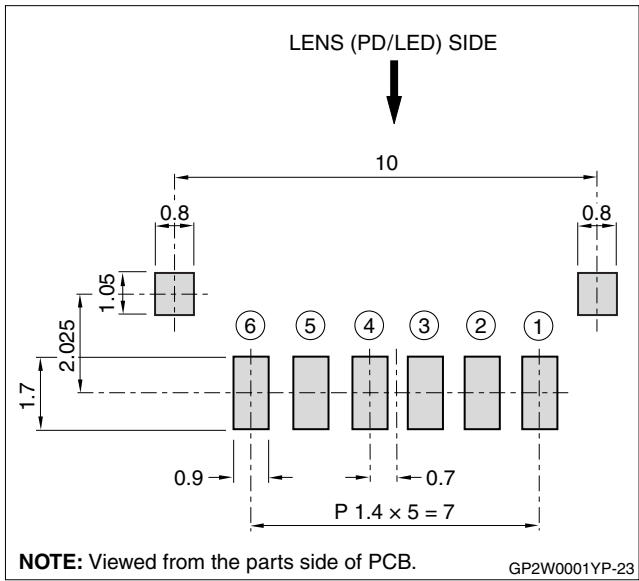


Figure 4. GP2W0002YP Soldering Footprint

Table 1. Pinouts

| PIN NO. | DESCRIPTION | SYMBOL |
|---------|-------------------------|-----------------|
| 1 | LED Anode | LEDA |
| 2 | Transmitter Data Input | TxD |
| 3 | Shut Down Circuit Input | SD |
| 4 | Receiver Data Output | RxD |
| 5 | Ground | GND |
| 6 | Supply Voltage | V _{CC} |

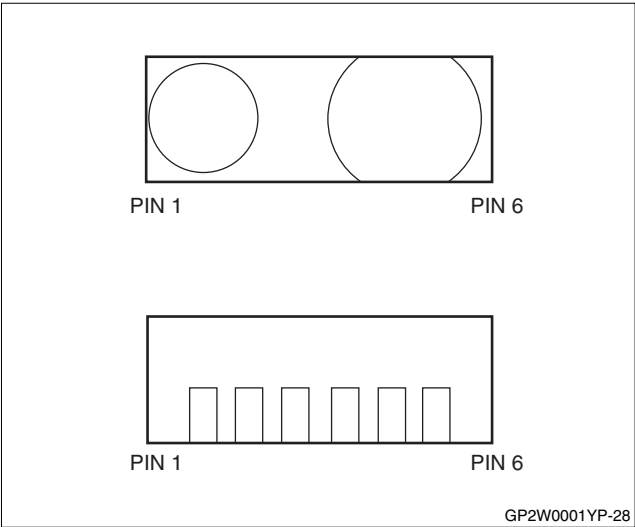


Figure 5. Pin Locations

ABSOLUTE MAXIMUM RATINGS

| PARAMETER | SYMBOL | MIN. | MAX. | UNIT | CONDITIONS | NOTES |
|--------------------------|-----------|------|------|------|--------------------------------|---------|
| Supply Voltage | V_{CC} | 0 | 6.0 | V | | |
| Peak Forward LED Current | I_{FM} | | 500 | mA | Pulse 78.1 ms, 3/16-duty cycle | 1, 2, 3 |
| Operating Temperature | T_{OPR} | -10 | +70 | °C | | 3 |
| Soldering Temperature | T_{SOL} | | 230 | °C | Solder reflow time: 5 seconds | |
| Storage Temperature | T_{STG} | -20 | +85 | °C | | |

NOTES:

1. An in-band optical signal is a pulse/sequence where the peak wavelength, λ_p , is defined as $850\text{ nm} < \lambda_p < 900\text{ nm}$, and the pulse characteristics are compliant with the IrDA Physical Layer

2. See 'IrDA Physical Layer Link Specification, Appendix A' for ambient light conditions.

3. See Figure 6.

RECOMMENDED OPERATING CONDITIONS

| PARAMETER | SYMBOL | MIN. | MAX. | UNIT | NOTES |
|---|-------------|----------------|----------|--------|-------|
| Supply Voltage | V_{CC} | 2.7 | 5.5 | V | |
| Logic High Transmitter Input Voltage (TxIN) | V_{IHTXD} | 2.4 | V_{CC} | V | 1 |
| Logic Low Transmitter Input Voltage (TxIN) | V_{ILTXD} | | 0.4 | V | |
| Shutdown Circuit High Level Input Voltage | V_{IHSD} | $V_{CC} - 0.6$ | V_{CC} | V | |
| Shutdown Circuit Low Level Input Voltage | V_{ILSD} | 0.0 | 0.4 | V | 2 |
| Data Rate | BR | 2.4 | 115.2 | kbit/s | |
| Operating Temperature | T_{OPR} | -10 | 70 | °C | |

NOTES:

1. Measured at the input circuit, not the device pin. Tx input should not exceed $0.8 V_{CC}$.

2. 0.4 or Open

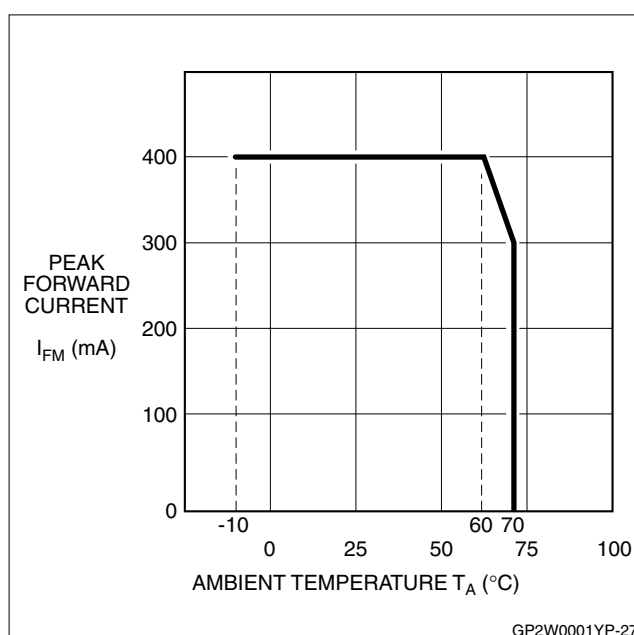


Figure 6. Peak Forward Current vs. Temperature

ELECTRICAL AND OPTICAL SPECIFICATIONS

| PARAMETER | SYMBOL | MIN. | TYP. | MAX. | UNIT | CONDITIONS | NOTES |
|----------------------------|-------------|------------|------|----------|------------------|--|-------|
| Supply Voltage | V_{CC} | 2.7 | | 5.5 | V | | |
| Maximum Reception Distance | L1 | ≥ 0.2 | | | m | $2\Theta_{1/2} \leq 15^\circ$, $I_E = 3.6 \text{ mW/sr}$ | |
| | L2 | ≥ 1.0 | | | m | $2\Theta_{1/2} \leq 15^\circ$, $I_E = 40 \text{ mW/sr}$ | |
| Data Rate | BR | 2.4 | | 115.2 | kbit/s | | |
| Operating Temperature | T_{OPR} | -10 | | 70 | $^\circ\text{C}$ | | |
| RECEIVER | | | | | | | |
| High Level Output Voltage | V_{OH} | 4.5 | | | V | $V_{CC} = 5 \text{ V}$ | |
| | V_{OH} | 2.5 | | | V | $V_{CC} = 3 \text{ V}$ | |
| Low Level Output Voltage | V_{OL1} | | | 0.6 | V | $V_{CC} = 5 \text{ V}$, $I_{OL} = 400 \text{ mA}$ RxD = ON | 3 |
| | V_{OL2} | | | 0.6 | V | $V_{CC} = 3 \text{ V}$, $I_{OL} = 400 \text{ mA}$ RxD = ON | 3 |
| Viewing Angle | 2Θ | 30 | | | degrees | | |
| Low Level Pulse Width | t_{W1} | 0.8 | | 16 | μs | BR = 2.4 kbit/s (pulse width 78.12 μs) | |
| | t_{W2} | 0.8 | | 8 | μs | BR = 115.2 kbit/s (pulse width 1.63 μs) | |
| | I_{CC1} | | 1.0 | 1.4 | mA | No input signal, $V_{CC} = 5.0 \text{ V}$, output open, $V_{IHSD} = V_{CC} - 0.6 \text{ V}$ | |
| Current Consumption | | | 0.7 | 1.0 | mA | No input signal, $V_{CC} = 3.0 \text{ V}$, output open, $V_{IHSD} = V_{CC} - 0.6 \text{ V}$ | |
| | I_{CC2} | | | 1.0 | μA | Shut-down Mode | |
| Rise Time | t_R | | | 1.2 | μs | | 3 |
| Fall Time | t_F | | | 0.2 | μs | | 3 |
| TRANSMITTER | | | | | | | |
| Radiant Intensity | I_{E1} | 3.6 | | 28.8 | mW/sr | $I_F = 27 \text{ mA}$, $2\Theta_{1/2} \leq 15^\circ$ | |
| | I_{E2} | 40 | | 350 | mW/sr | $I_F = 300 \text{ mA}$, $2\Theta_{1/2} \leq 15^\circ$ | |
| Peak Emission Wavelength | λ_p | 850 | 870 | 900 | nm | $I_F = 20 \text{ mA}$ | |
| Peak LED Current | I_{LEDA} | | 500 | | mA | All modes, PW = 78.1 μs or less, 3/16 duty cycle | |
| High Level Input Voltage | V_{IH} | 2.4 | | V_{CC} | V | Measured at input circuit. Device pin will usually not exceed 0.8 V | |
| Low Level Input Voltage | V_{IL} | 0.0 | | 0.4 | V | | |

NOTES:

- These specifications reflect the Recommended Operating Conditions, unless otherwise noted.
- All typical values are at 25 $^\circ\text{C}$ and 3.3 V, ambient light on the receiver surface under 10 Lux, unless otherwise noted.
- See Figure 7, Figure 8, and Figure 9

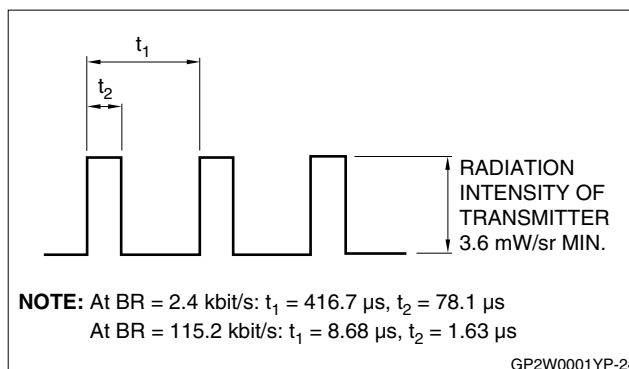


Figure 7. Detector Input Signal Waveform

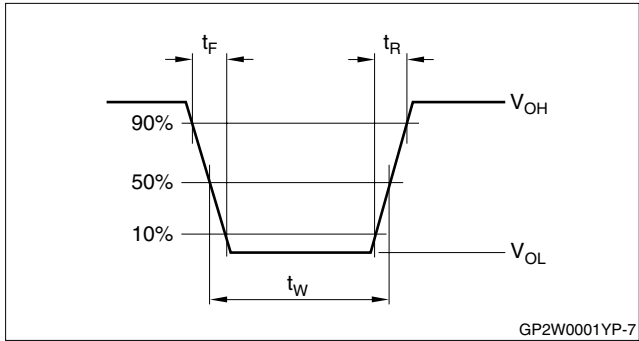


Figure 8. Output Waveform Specification

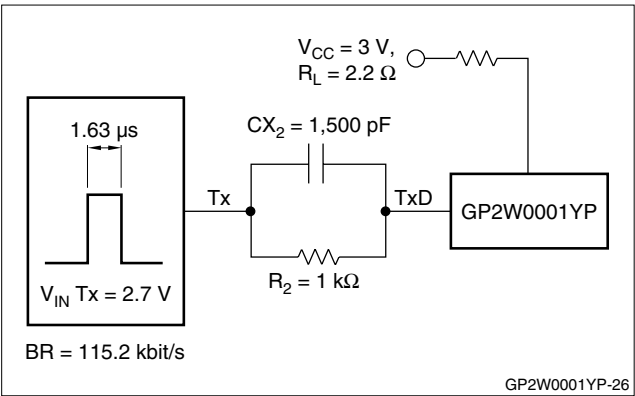


Figure 9. Recommended Emitter Circuit

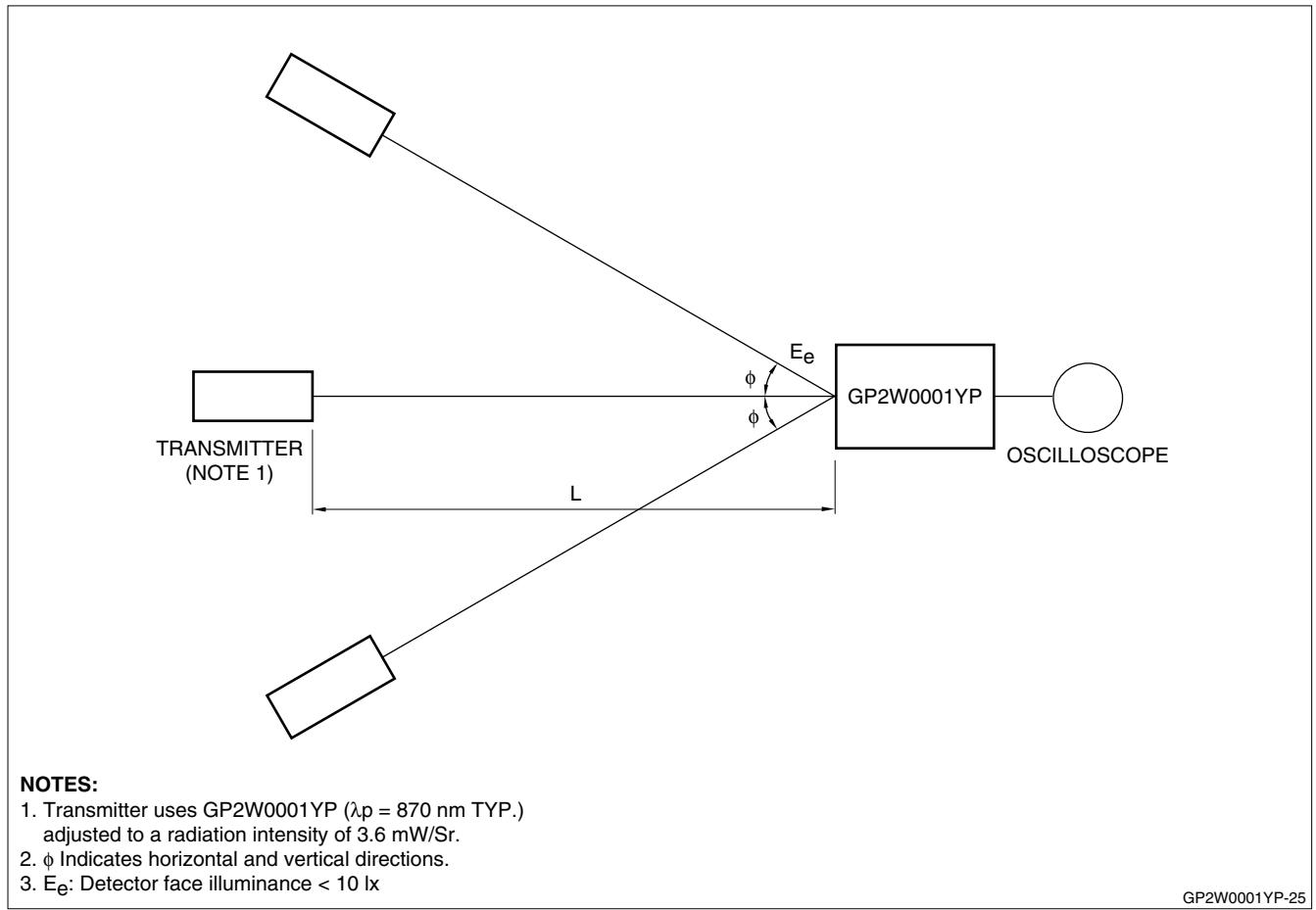


Figure 10. Standard Optical Detector System

ELECTRICAL DESIGN APPLICATION TIPS

Figure 11 shows a circuit application and passive component values for a GP2W0001YP. The values shown are only for reference.

Circuit Application and External Passive Components

The circuit application and the external passive components shown in Figure 11 enable the GP2W0001YP to operate at both one-meter and 20 cm low power option communication modes at $V_{CC} = 3.0\text{ V}$.

SHUTDOWN MODE

The ‘Shutdown’ pin is an active LOW terminal.

Shutdown mode only affects the power consumption of the receiver circuits. The transmitter LED can still be operated when SD is asserted. The two circuits are independent and not internally connected. The transmitter circuit does not consume current unless a drive signal is applied.

Table 2. SD Pin Functions

| INPUT | PERFORMANCE |
|-------|---------------|
| HIGH | Normal Mode |
| LOW | Shutdown Mode |
| OPEN | Shutdown Mode |

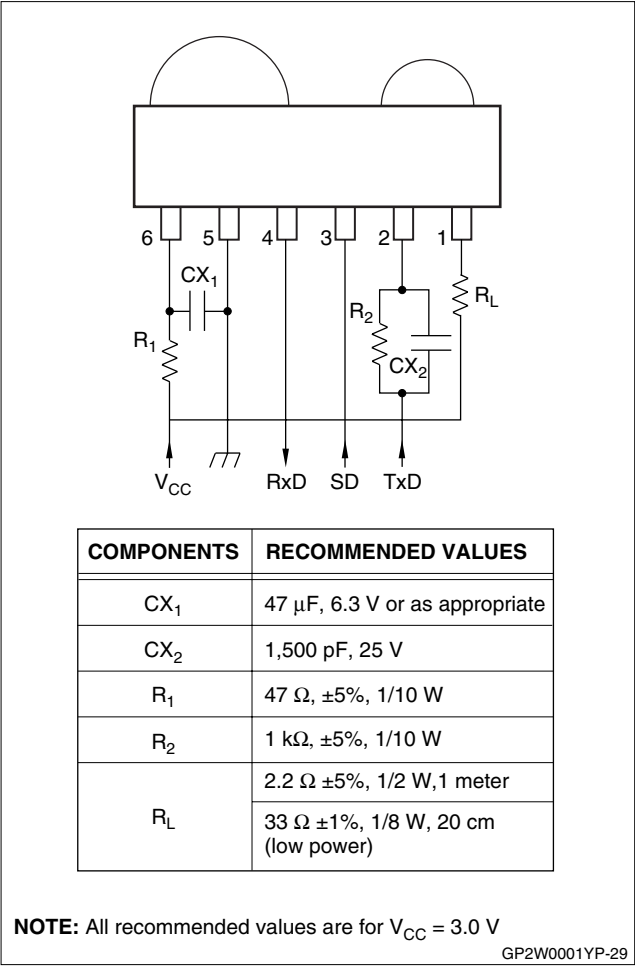


Figure 11. External Components

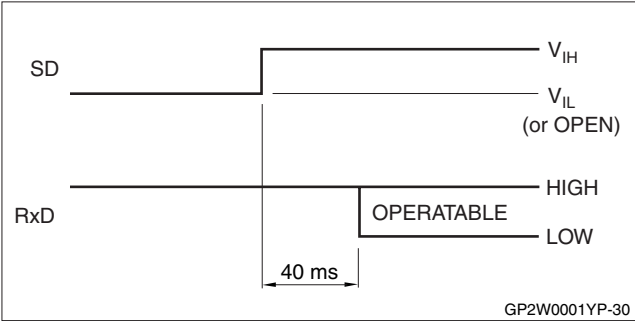


Figure 12. Receiver Activation

Signal Waveform Example

Figure 14 shows examples of each waveform when operating a GP2W0001YP to IrDA standards. Note that the IrDA bitstream is inverted in the encoder and decoder circuits, and the output pulse is sent during a '0' bit. The examples are for reference only, to help understand the GP2W0001YP hardware, and device signal measurements. The receiver output is not gated, and will send output for the entire period of the received IR input signal. Refer to Figure 14 for waveform reference points.

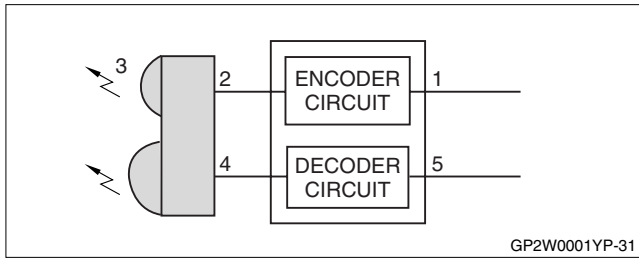


Figure 13. GP2W0001YP Block Diagram

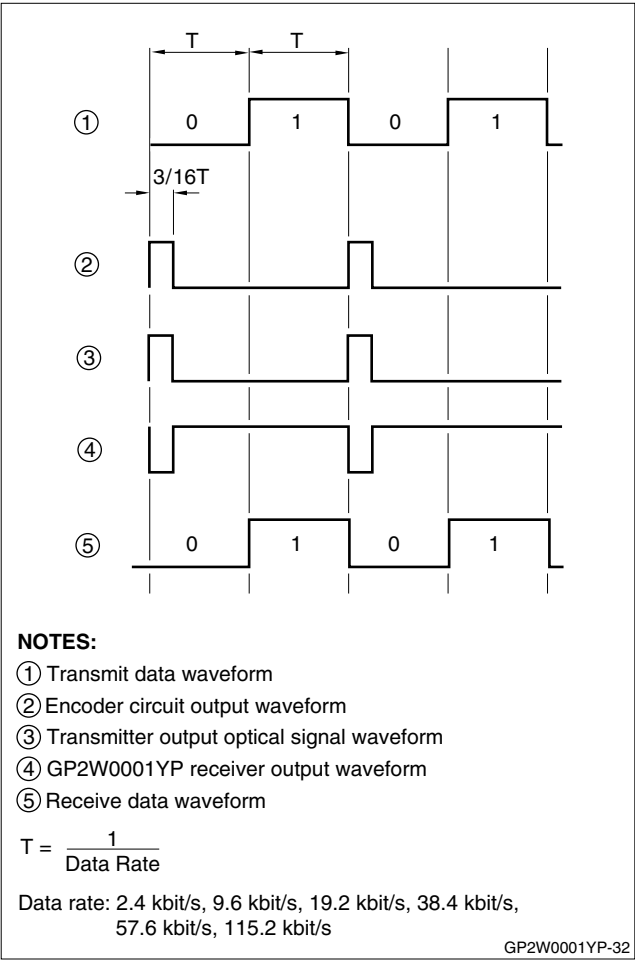


Figure 14. Signal Waveform Example

MECHANICAL DESIGN APPLICATION TIPS

Recommended Footprint

Figure 15 shows the basic recommended footprint for PCB design using the SHARP GP2W0001YP infrared transceiver module. All values shown here are for reference, and are in mm.

Electro-Mechanical Design Tip

Figure 16 gives a recommended set of locations for resistors and capacitors for better performance, particularly for the power supply (V_{CC}) line. R_1 and CX_1 , as shown in Figure 16, should be mounted near the GP2W0001YP transceiver module for best performance. All values in Figure 16 are for reference and are in mm.

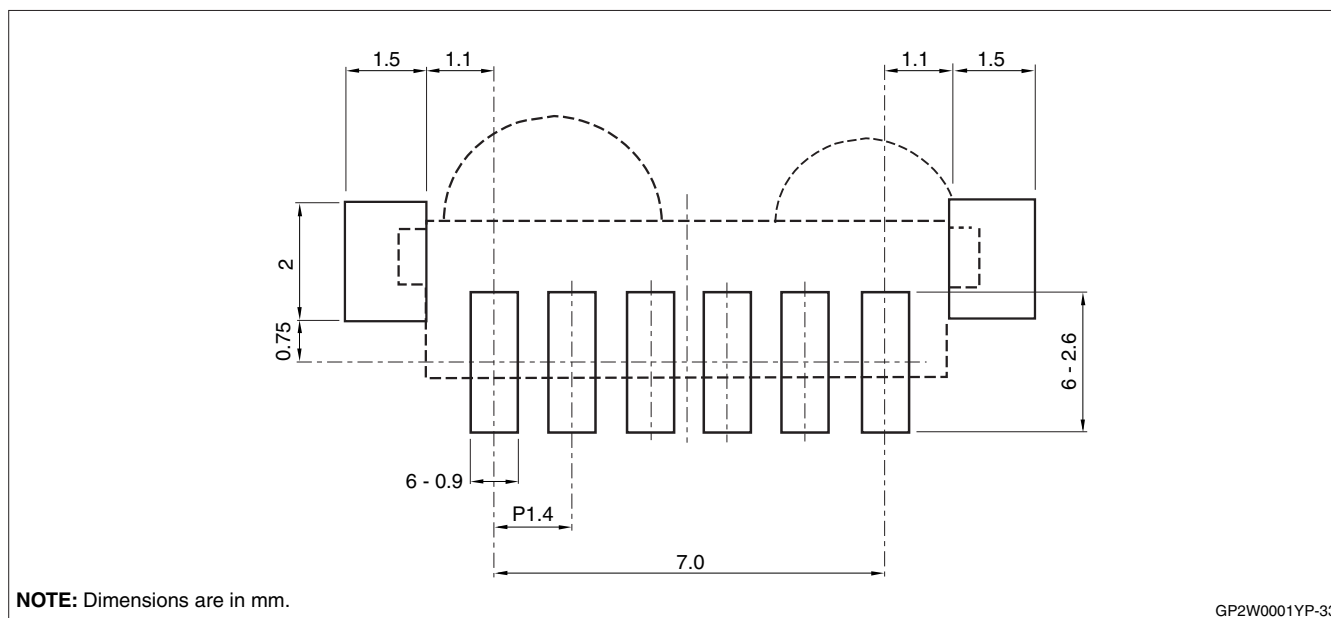
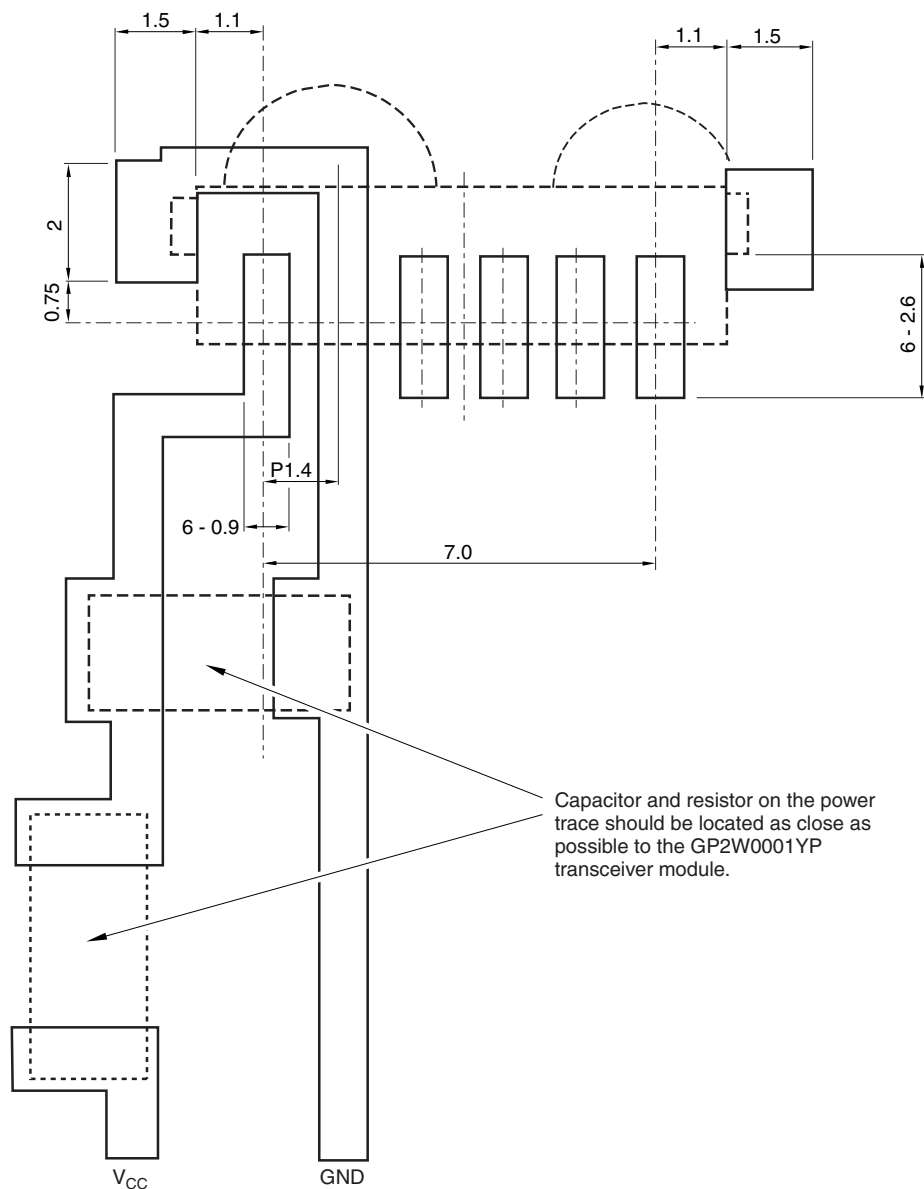


Figure 15. Recommended Footprint



NOTE: Dimensions are in mm.

GP2W0001YP-34

Figure 16. PCB Design Tip

Cabinet and IR Cosmetic Window Design Tips

Figure 17 with its calculations illustrates the design tips for a cabinet and an IR cosmetic window with $\pm 18^\circ$ viewing angles in the vertical and horizontal axes. All transceiver dimension values are for reference, and are in mm.

The optical window size should be the minimum size of $W \times H$, either rectangular or elliptical, to maintain

IrDA data transfer performance. The dimensions for W can be calculated by the formula:

$$W = 2 \times L \times \tan(18^\circ + w)$$

And the dimensions for H can be calculated by the formula:

$$H = 2 \times L \times \tan(18^\circ + h)$$

In the case where the viewing angle is $+18^\circ$, which conforms to or exceeds the IrDA Serial Infrared Physical Layer Link Specifications. Values to be calculated with above the formula must be given in mm.

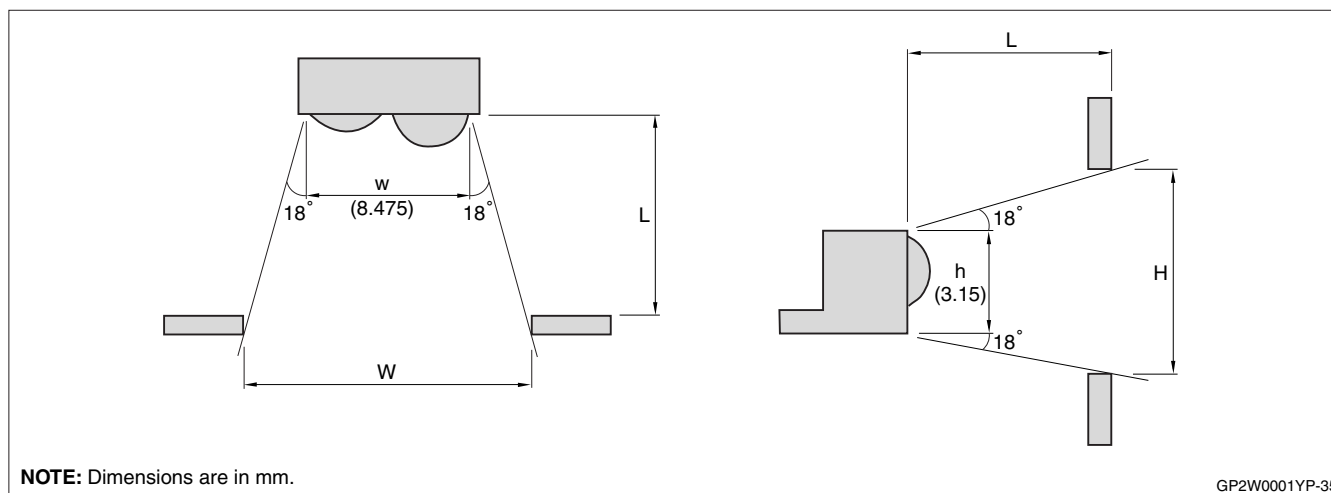


Figure 17. Optical Window Tips

Evaluation Board

Figure 18 shows the recommended evaluation circuit for the GP2W0001YP/GP2W0002YP devices. This circuit is provided on an evaluation board for test and evaluation purposes. Samples are available through your Sharp support office or Sales Representative.

The resistor value for R_L is based on the supply voltage. For the one-meter range, the parallel combination of the three values should be adjusted to approximately $2.2\ \Omega$ when $V_{CC} = 3.3\text{ V}$, yielding a forward current of 300 mA with approximately 200 mW being dissipated in the resistors. For the 20 cm (reduced) range, the value is adjusted to $33\ \Omega$, the nominal forward current is 27 mA, and the resistive power dissipation will be approximately 31 mW.

When the 33 Ω value and a forward current of 27 mA is used, a total of 31.3 mW is dissipated during LED on-time. This dissipation is within the rating of the SR1206 package. When used at a data rate of 115 kbit/s, the maximum on time is 18.75% of a bit time when the LED is 'ON.' Since only the logical '0' values of a data string are sent, the overall duty cycle is below this value.

The board carries three positions to allow the use of a combination of standard resistor values. To create the 2.2 Ω value, three 6.6 Ω resistors are connected in parallel. For the 43 Ω value, one 43 Ω resistor can be used or three parallel resistors of 130 Ω . The resistor positions on the board are in the SR1206 footprint, which supports one-quarter Watt resistors.

This test and evaluation board is not intended for production applications, and should not be subjected to long periods at elevated temperature. Operation of the board should be limited to free-air test conditions.

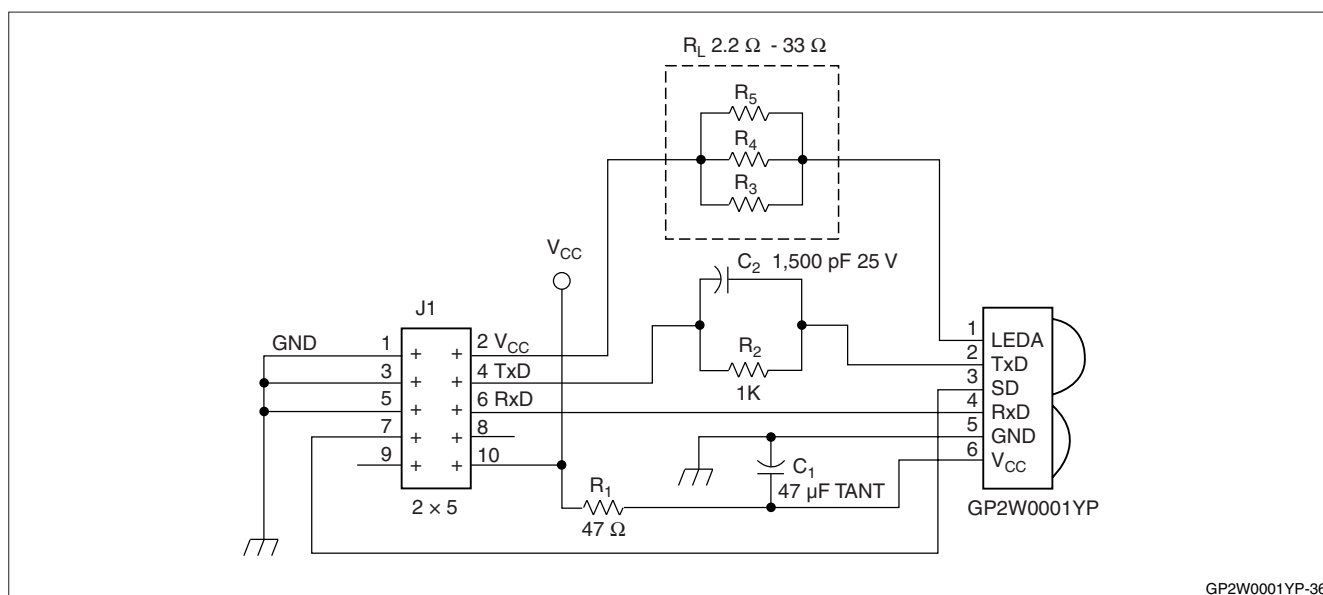


Figure 18. GP2W0001YP Test Circuit

MOISTURE-PROOF PACKING INFORMATION

Scope

This section describes the specifications of GP2W0001YP/GP2W0002YP moisture-proof packing, and is only for reference. The official specifications should be consulted for packing information.

Packing Material Specifications

The GP2W0001YP/GP2W0002YP reel is moisture-proof packed for shipment. Table 3 describes the materials used for each item of the moisture-proof packing.

Packing Method

1. Seal the aluminum laminate bag that contains the tape reel (2,000 devices/reel) and desiccant.
2. Fill in the necessary information on the label and paste it on the aluminum laminate bag.
3. Pack 4 aluminum laminated bags (1 reel each) into the designated outer case, placing paper pads on the bottom and top of the outer case, as well as between each layer of the aluminum laminated bags. See Table 4.
4. Seal the outer case with craft tape, indicating the model name, quantity, and out-going inspection date on the case. (8,000 pieces total per carton)

Storage and Treatment

STORAGE CONDITIONS

The product should be stored under these conditions:

- Storage temperature: 10°C to 30°C
- Humidity: below 60% RH

TREATMENT AFTER UNSEALING

1. After unsealing, devices should be mounted at a temperature of 10°C to 30°C, humidity below 60% RH, within 3 days.
2. For long term storage, devices should either be stored in a dry box, or re-sealed in a moisture-proof bag with desiccant and stored in an environment where the temperature is 10°C to 30°C, humidity below 60% RH. Devices must be mounted within 2 weeks.

BAKING BEFORE MOUNTING

If the devices are not kept in the storage conditions described above, or the desiccant indicator has turned pink, baking must be performed before devices are mounted: baking may only be done once.

- Recommended Baking Conditions: 100°C
12 to 24 hours

NOTE: Do not bake the devices while they are still on the reel — the reel will melt. Parts should be either temporarily mounted to a PCB with adhesive, or placed in a metal tray. Any device that has been out of its dry pack for more than 72 hours should be dried in some manner prior to any automated surface mount reflow process. Otherwise these devices should be mounted and soldered by hand.

Table 3. Packing Materials

| ITEM | MATERIAL |
|-----------------------|-----------------------|
| Aluminum Laminate Bag | Aluminum Polyethylene |
| Label | Paper |
| Desiccant | |
| Outer Case | Paper |
| Pads | Paper |

Table 4. Packing Quantities

| PACKING SHAPE | PRODUCT | QUANTITY PER REEL | QUANTITY PER BAG |
|----------------------|---------|-------------------|------------------|
| Tape reel (Ø 330 mm) | 1 model | 2,000 pieces | 1 reel |

NOTE: Minimum order/shipment quantity should be one laminated bag (1 reel of 2,000 pieces).

SPECIFICATIONS ARE SUBJECT TO CHANGE WITHOUT NOTICE.

Suggested applications (if any) are for standard use; See Important Restrictions for limitations on special applications. See Limited Warranty for SHARP's product warranty. The Limited Warranty is in lieu, and exclusive of, all other warranties, express or implied. ALL EXPRESS AND IMPLIED WARRANTIES, INCLUDING THE WARRANTIES OF MERCHANTABILITY, FITNESS FOR USE AND FITNESS FOR A PARTICULAR PURPOSE, ARE SPECIFICALLY EXCLUDED. In no event will SHARP be liable, or in any way responsible, for any incidental or consequential economic or property damage.

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